

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	75	(@ad<"20010110") and (wafer adj cap) and (method or form or process or make or manufacture)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 13:34
L2	55	(@ad<"20010110") and (wafer adj cap) and (mold or plate or press or pressure or move or molding or die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 11:59
L3	5	L2 not L1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 12:01
L4	960	(@ad<"20010110") and (wafer near (cap or lid or cover)) and (method or form or process or make or manufacture)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 12:00
L5	1015	(@ad<"20010110") and (wafer near (cap or lid or cover)) and (method or form or process or make or manufacture or mold or plate or press or pressure or move or molding or die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 16:12
L6	671	L5 and (mold or plate or press or pressure or move or molding or die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 13:37
L7	621	L6 not L1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 12:01
L8	616	L7 not L2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 12:01

L9	616	L8 not L3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 12:02
L10	449	L9 and (cavity or cavities or recess or groove or trench or via or hole or opening)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 15:35
L11	54	("5915168").URPN.	USPAT	OR	OFF	2005/06/06 12:22
L12	7	("4990814" "5059848" "5567656" "5583373" "5593927" "5604160" "5610431").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/06/06 12:22
L13	6	("4921564" "5313835" "5326726" "5435876" "5447068" "5597767").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/06/06 12:25
L14	36	("5824177").URPN.	USPAT	OR	OFF	2005/06/06 12:26
L15	1127	(@ad<"20010110") and 257/704, 710.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 13:37
L16	603	L15 and (mold or plate or press or pressure or move or molding or die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 15:37
L17	594	L16 not L10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 13:38
L18	5	("4303934" "5173841" "5184209" "5189638" "5210442").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/06/06 14:17
L19	4	("4303934" "5173841" "5184209" "5189638" "5210442").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/06/06 14:46
L20	182403	(mold or molding) with (cavity or cavities or recess or groove or trench or via or hole or opening)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 15:35

L21	114	L20 and (@ad<"20010110") and (wafer with (cap\$1 or lid\$1 or cover\$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 16:03
L22	114	L21 and (mold or plate or press or pressure or move or molding or die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 16:31
L23	4	53/109,471,485.ccls. and (@ad<"20010110") and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 16:05
L24	28	("5694740").URPN.	USPAT	OR	OFF	2005/06/06 16:05
L25	1	156/262,393.ccls. and (@ad<"20010110") and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 16:06
L26	10	257/924.ccls. and (@ad<"20010110") and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 16:07
L27	3	264/268.ccls. and (@ad<"20010110") and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 16:07
L28	0	100/54.ccls. and (@ad<"20010110") and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 16:07
L29	0	100/59.ccls. and (@ad<"20010110") and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 16:12

L30	1224	(@ad<"20010110") and (wafer near (cap or lid or cover))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 16:13
L31	10028	(@ad<"20010110") and (wafer with (cap\$1 or lid\$1 or cover\$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 16:32
L32	1511	(@ad<"20010110") and (wafer near (cap\$1 or lid\$1 or cover\$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 16:14
L33	931	L32 and (place or mold or plate or press or pressure or move or molding or die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 16:14
L34	482	L33 not L10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 16:15
L35	251	L34 not L4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 16:15
L36	251	L35 not L1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 16:15
L37	68164	(etch or etching)with (mold or plate or press or pressure or move or molding or die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 16:31

L38	68164	(etch or etching) with (mold or plate or press or pressure or move or molding or die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 17:24
L39	766	L38 and (@ad<"20010110") and (wafer with (cap\$1 or lid\$1 or cover\$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 16:32
L40	103	L38 and (@ad<"20010110") and (wafer near (cap\$1 or lid\$1 or cover\$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 16:58
L41	1176	L30 not L36	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 16:33
L42	72	L40 not L36	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 16:33
L43	1	("5915168").PN	USPAT	OR	OFF	2005/06/06 16:48
L44	131	(encapsulant or encapsulater) and ((etch or etching) with (mold or molding))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 16:55
L45	251	(encapsulant or encapsulate) and ((etch or etching) with (mold or molding))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 16:51
L46	32	L45 and ((silicon or "si") with (mold or molding))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 16:52

L47	6603	((etch or etching) with (mold or molding))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 16:55
L48	12	L47 and (@ad<"20010110") and (wafer near (cap\$1 or lid\$1 or cover\$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 17:23
L49	46568	(etch or etching) with (mold or plate or press or molding or die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 16:58
L50	15039	L49 and (((upper and lower) or (first and second) or (top and bottom))) with (mold or plate or press or molding or die))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 16:58
L51	2137	L50 and (@ad<"20010110") and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 16:59
L52	5248	(etch or etching) near (mold or plate or press or molding or die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 17:10
L53	1773	L52 and (((upper and lower) or (first and second) or (top and bottom))) with (mold or plate or press or molding or die))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 16:58
L54	193	L53 and (@ad<"20010110") and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 17:11

L55	7	L54 and (wafer near (cap\$1 or lid\$1 or cover\$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 17:00
L56	186	L54 not L55	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 17:00
L57	924	(lithography or photolithography) near (mold or plate or press or molding or die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 17:10
L58	10104959	L57 (mold or place or plate or press or pressure or move or molding or die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 17:11
L59	924	L57 and (mold or place or plate or press or pressure or move or molding or die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 17:11
L60	89	L59 and (@ad<"20010110") and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 17:15
L61	9812	(mold or molding).ti. and (@ad<"20010110") and (encapsulant or encapsualte or cap\$1 or cover\$1 or lid\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 17:17
L62	0	(mold or molding).tti. and (@ad<"20010110") and (encapsulant or encapsualte or cap\$1 or cover\$1 or lid\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 17:16

L63	0	(mold or molding).tti. and (@ad<"20010110")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 17:16
L64	72	L61 and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 17:17
L65	707	(sheet or strip or film) and (@ad<"20010110") and (wafer near (cap\$1 or lid\$1 or cover\$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 17:23
L66	451	L65 and (mold or plate or press or pressure or move or molding or die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 17:24
L67	103	L66 not L4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/06 17:24